SECTION 1 - SERVICING

1. Preventive Maintenance Procedures

Contains routine maintenance instructions for cleaning and inspecting the Test Set.

CAUTION: DISCONNECT POWER FROM TEST SET TO AVOID POSSIBLE DAMAGE TO ELECTRONIC CIRCUITS.

A. External Cleaning

STEP PROCEDURE

- 1. Clean front panel, switches and display face with soft lint-free cloth. If dirt is difficult to remove, dampen cloth with water and mild liquid detergent.
- 2. Remove grease, fungus and ground-in dirt from surfaces with soft lint-free cloth dampened (not wet) with isopropyl alcohol.
- 3. Remove dust and dirt from connectors with soft-bristled brush.
- Cover connectors, not in use, with suitable dust cover to prevent tarnishing of connector contacts.
- 5. Clean cables with soft lint-free cloth.
- 6. Paint exposed metal surface to avoid corrosion.

B. Internal Cleaning



THIS EQUIPMENT CONTAINS PARTS
SENSITIVE TO DAMAGE
BY ELECTROSTATIC DISCHARGE (ESD)

CAUTION: AVOID MOVING COMPONENTS ON CIRCUIT BOARDS OR DISASSEMBLING

CONNECTORS NEEDLESSLY TO PREVENT POSSIBLE DAMAGE.

CAUTION: AVOID OPENING COMPLEX INTERNAL MODULES FOR THE SOLE PURPOSE

OF CLEANING AND INSPECTION.

STEP PROCEDURE

- 1. Remove dust with hand-controlled dry air jet of 15 psi (1.054 kg/cm²) and wipe internal chassis parts and frame with soft lint-free cloth moistened with alcohol.
- 2. Clean switches and controls with contact cleaner.

C. Visual Inspection

STEP PROCEDURE

- 1. Inspect Chassis for:
 - Tightness of sub-assemblies and chassis mounted connectors.
 - Corrosion or damage to metal surfaces.
- 2. Inspect Capacitors for:
 - Loose mounting, deformities or obvious physical damage.
 - Leakage or corrosion around leads.
- 3. Inspect Connectors for loose or broken parts, cracked insulation and bad contacts.
- 4. Inspect Controls for correct rotation.
- 5. Inspect Circuit Boards for:
 - Corrosion or damage to connectors.
 - Damage to mounted components including crystals and ICs.
 - Freedom from foreign material.
- 6. Inspect Resistors for:
 - Cracked, broken, charred or blistered bodies.
 - Loose or corroded soldering connections.
- 7. Inspect Semiconductors for:
 - Cracked, broken, charred or discolored bodies.
 - Seals around leads being in place and in good condition.
- 8. Inspect Switches for:
 - Loose levers, terminals and switch body contact to frame.
 - Bent or loose line switch contacts.
- 9. Inspect Wiring for:
 - Broken or loose ends and connections.
 - Proper dress relative to other chassis parts.

NOTE: Verify laced wiring is tight with ends securely tied.